

# INA300-Q1 Automotive-Grade, High- or Low-Side, Current-Sense Comparator

## 1 Features

- Qualified for Automotive Applications
- AEC-Q100 Qualified With the Following Results:
  - Device Temperature Grade 1:  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$  Ambient Operating Temperature
  - Device HBM ESD Classification Level 2
  - Device CDM ESD Classification Level C6
- Wide Common-Mode Range: 0 V to 36 V
- Selectable Response Times:
  - 10  $\mu\text{s}$ , 50  $\mu\text{s}$ , 100  $\mu\text{s}$
- Programmable Threshold:
  - Adjustable Using a Single Resistor
  - Programmable from 0 mV to 250 mV
- Accuracy:
  - Offset Voltage:  $\pm 500 \mu\text{V}$  (Max)
  - Offset Voltage Drift:  $0.5 \mu\text{V}/^{\circ}\text{C}$  (Max)
- Selectable Hysteresis:
  - 2 mV, 4 mV, 8 mV
- Active Quiescent Current: 135  $\mu\text{A}$  (Max)
- Open-Drain Output with Latch Mode Available

## 2 Applications

- Body Control Module
- Motor Control
- Valve Control
- Central Control Module

## 3 Description

The INA300-Q1 is a high common-mode, current-sensing comparator that is configured to detect overcurrent conditions through measuring the voltage developed across a current sensing or shunt resistor. The device can measure this differential voltage signal on common-mode voltages that can vary from 0 V up to 36 V, independent of the supply voltage. The device features an adjustable threshold range that is set using a single external limit-setting resistor. A selectable hysteresis feature enables adjustable operation of the comparator to accommodate the wide input signal range of 0 mV to 250 mV.

An open-drain alert output on the device can be configured to operate in either a transparent mode where the output status follows the input state or in a latched mode where the alert output is cleared when the latch is cleared. The device response time setting is selectable, enabling overcurrent alerts to be issued in as quickly as 10  $\mu\text{s}$ .

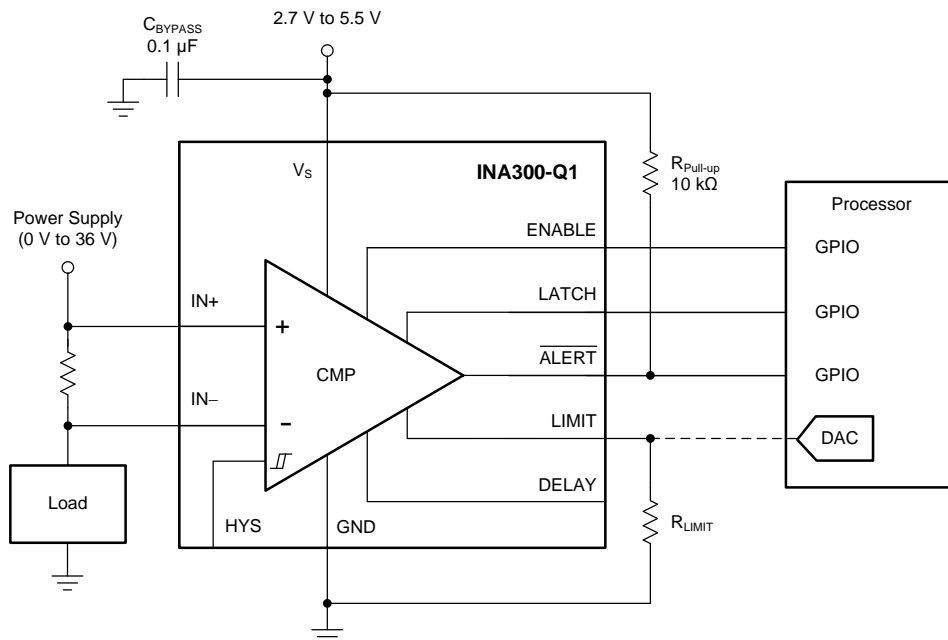
This device operates from a single 2.7-V to 5.5-V supply, drawing a maximum supply current of 135  $\mu\text{A}$ . The device is specified over the extended operating temperature range ( $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ ), and is available in a VSSOP-10 package.

Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
INA300-Q1	VSSOP (10)	3.00 mm x 3.00 mm

(1) For all available packages, see the package option addendum at the end of the data sheet.

## Typical Application



## 4 Device and Documentation Support

### 4.1 Documentation Support

#### 4.1.1 Related Documentation

For related documentation see the following:

- INA300EVM User's Guide, [SBAU220](#)

### 4.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

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### 4.3 Trademarks

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### 4.4 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 4.5 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 5 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
INA300AQDGSRQ1	PREVIEW	VSSOP	DGS	10		TBD	Call TI	Call TI	-40 to 125		

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

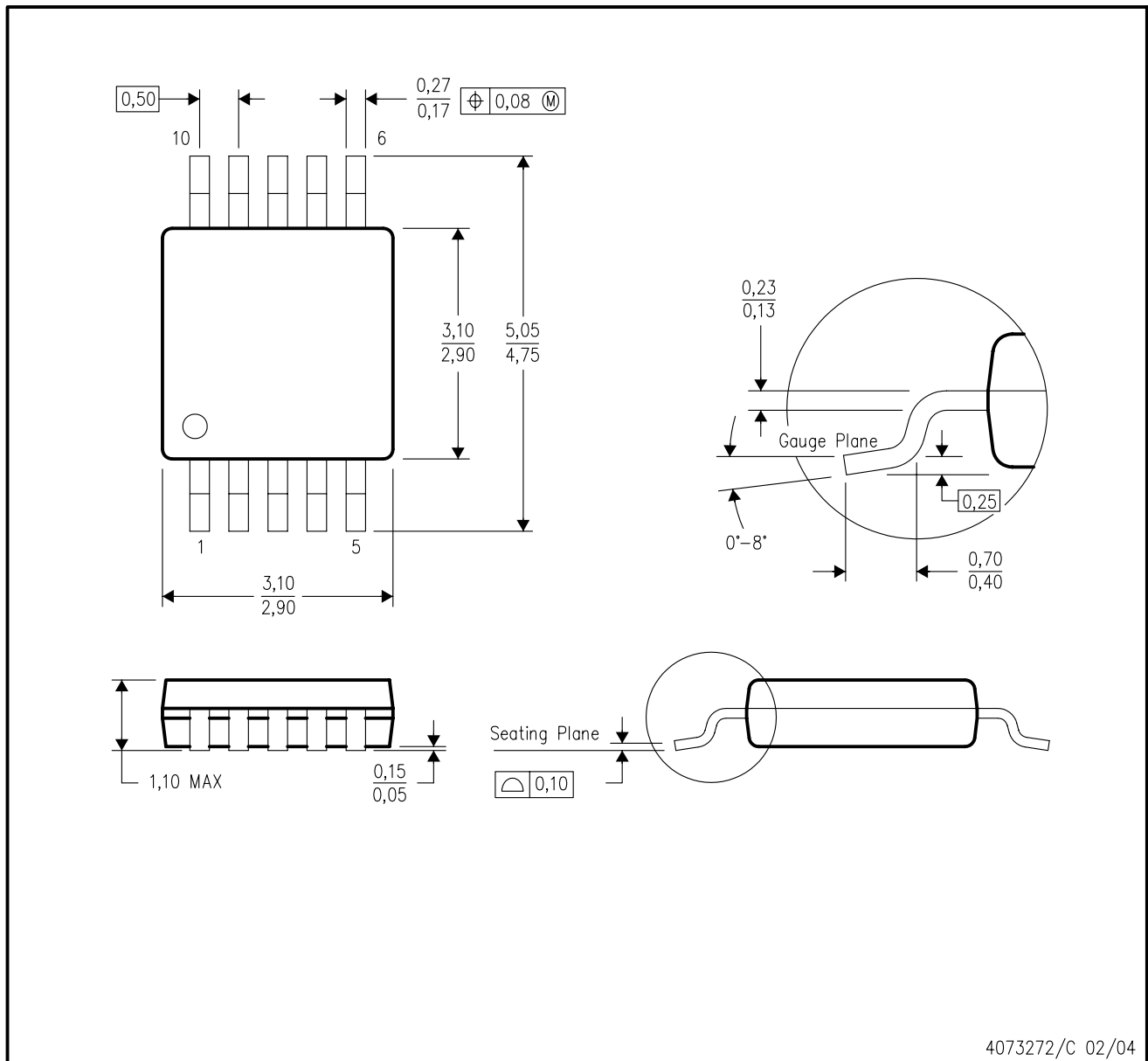
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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DGS (S-PDSO-G10)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion.
  - D. Falls within JEDEC MO-187 variation BA.

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Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
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Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
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### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
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Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
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Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
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